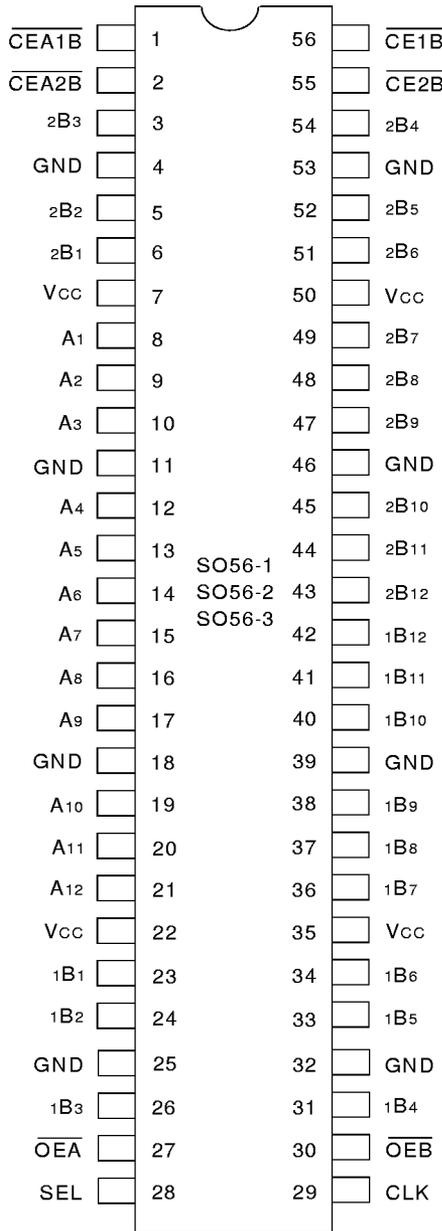




**PIN CONFIGURATION**



**SSOP/  
TSSOP/TVSOP  
TOP VIEW**

**ABSOLUTE MAXIMUM RATING (1)**

Symbol	Description	Max.	Unit
V <sub>TERM</sub> <sup>(2)</sup>	Terminal Voltage with Respect to GND	- 0.5 to + 4.6	V
V <sub>TERM</sub> <sup>(3)</sup>	Terminal Voltage with Respect to GND	- 0.5 to V <sub>CC</sub> + 0.5	V
T <sub>STG</sub>	Storage Temperature	- 65 to + 150	°C
I <sub>OUT</sub>	DC Output Current	- 50 to + 50	mA
I <sub>IK</sub>	Continuous Clamp Current, V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub>	± 50	mA
I <sub>OK</sub>	Continuous Clamp Current, V <sub>O</sub> < 0	- 50	mA
I <sub>CC</sub>	Continuous Current through each V <sub>CC</sub> or GND	± 100	mA

**NOTES:**

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. V<sub>CC</sub> terminals.
3. All terminals except V<sub>CC</sub>.

**CAPACITANCE (T<sub>A</sub> = +25°C, f = 1.0MHz)**

Symbol	Parameter <sup>(1)</sup>	Conditions	Typ.	Max.	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0V	5	7	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V	7	9	pF
C <sub>I/O</sub>	I/O Port Capacitance	V <sub>IN</sub> = 0V	7	9	pF

**NOTE:**

1. As applicable to the device type.

**PIN DESCRIPTION**

Pin Names	I/O	Description
Ax(1:12)	I/O	Bidirectional Data Port A. Usually connected to the CPU's Address/Data bus. <sup>(1)</sup>
1Bx(1:12)	I/O	Bidirectional Data Port 1B. Usually connected to the even path or even bank of memory. <sup>(1)</sup>
2Bx(1:12)	I/O	Bidirectional Data Port 2B. Usually connected to the odd path or odd bank of memory. <sup>(1)</sup>
CLK	I	Clock Input
$\overline{\text{CEA1B}}$	I	Clock Enable Input for the A-1B Register. If $\overline{\text{CEA1B}}$ is LOW during the rising edge of CLK, data will be clocked into register A-1B (Active LOW).
$\overline{\text{CEA2B}}$	I	Clock Enable Input for the A-2B Register. If $\overline{\text{CEA2B}}$ is LOW during the rising edge of CLK, data will be clocked into register A-2B (Active LOW).
$\overline{\text{CE1B}}$	I	Clock Enable Input for the 1B-A Register. If $\overline{\text{CE1B}}$ is LOW during the rising edge of CLK, data will be clocked into register 1B-A (Active LOW).
$\overline{\text{CE2B}}$	I	Clock Enable Input for the 2B-A Register. If $\overline{\text{CE2B}}$ is LOW during the rising edge of CLK, data will be clocked into register 2B-A (Active LOW).
SEL	I	1B or 2B Port Selection. When HIGH during the rising edge of CLK, SEL enables data transfer from 1B Port to A Port. When LOW during the rising edge of CLK, SEL enables data transfer from 2B Port to A Port.
$\overline{\text{OEA}}$	I	Synchronous Output Enable for A Port (Active LOW).
$\overline{\text{OEB}}$	I	Synchronous Output Enable for 1B Port and 2B Port (Active LOW).

**NOTE:**

1. These pins have "Bus-Hold." All other pins are standard inputs, outputs, or I/Os.

**FUNCTION TABLES<sup>(1)</sup>**

Inputs							Output
1Bx	2Bx	SEL	$\overline{\text{CE1B}}$	$\overline{\text{CE2B}}$	$\overline{\text{OEA}}$	CLK	Ax
H	X	H	L	X	L	—	H
L	X	H	L	X	L	—	L
X	X	H	H	X	L	—	Ao <sup>(2)</sup>
X	H	L	X	L	L	—	H
X	L	L	X	L	L	—	L
X	X	L	X	H	L	—	Ao <sup>(2)</sup>
X	X	X	X	X	H	—	Z

Inputs					Outputs	
Ax	$\overline{\text{CEA1B}}$	$\overline{\text{CEA2B}}$	$\overline{\text{OEB}}$	CLK	1Bx	2Bx
H	L	L	L	—	H	H
L	L	L	L	—	L	L
H	L	H	L	—	H	Bo <sup>(2)</sup>
L	L	H	L	—	L	Bo <sup>(2)</sup>
H	H	L	L	—	Bo <sup>(2)</sup>	H
L	H	L	L	—	Bo <sup>(2)</sup>	L
X	H	H	L	—	Bo <sup>(2)</sup>	Bo <sup>(2)</sup>
X	X	X	H	—	Z	Z
X	X	X	L	—	Active	Active

**NOTES:**

- H = HIGH Voltage Level  
L = LOW Voltage Level  
X = Don't Care  
Z = High-Impedance
- Output level before the indicated steady-state input conditions were established.

## DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: TA = - 40 °C to +85 °C

Symbol	Parameter	Test Conditions		Min.	Typ. <sup>(1)</sup>	Max.	Unit
V <sub>IH</sub>	Input HIGH Voltage Level	V <sub>CC</sub> = 2.3V to 2.7V		1.7	—	—	V
		V <sub>CC</sub> = 2.7V to 3.6V		2	—	—	
V <sub>IL</sub>	Input LOW Voltage Level	V <sub>CC</sub> = 2.3V to 2.7V		—	—	0.7	V
		V <sub>CC</sub> = 2.7V to 3.6V		—	—	0.8	
I <sub>IH</sub>	Input HIGH Current	V <sub>CC</sub> = 3.6V	V <sub>I</sub> = V <sub>CC</sub>	—	—	± 5	μA
I <sub>IL</sub>	Input LOW Current	V <sub>CC</sub> = 3.6V	V <sub>I</sub> = GND	—	—	± 5	
I <sub>OZH</sub>	High Impedance Output Current (3-State Output pins)	V <sub>CC</sub> = 3.6V	V <sub>O</sub> = V <sub>CC</sub>	—	—	± 10	μA
I <sub>OZL</sub>			V <sub>O</sub> = GND	—	—	± 10	μA
V <sub>IK</sub>	Clamp Diode Voltage	V <sub>CC</sub> = 2.3V, I <sub>IN</sub> = - 18mA		—	- 0.7	- 1.2	V
V <sub>H</sub>	Input Hysteresis	V <sub>CC</sub> = 3.3V		—	100	—	mV
I <sub>CC1</sub>	Quiescent Power Supply Current	V <sub>CC</sub> = 3.6V		—	0.1	40	μA
I <sub>CC2</sub>		V <sub>IN</sub> = GND or V <sub>CC</sub>					
I <sub>CC3</sub>							
ΔI <sub>CC</sub>	Quiescent Power Supply Current Variation	One input at V <sub>CC</sub> - 0.6V, other inputs at V <sub>CC</sub> or GND		—	—	750	μA

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**NOTE:**

1. Typical values are at V<sub>CC</sub> = 3.3V, +25 °C ambient.

## BUS-HOLD CHARACTERISTICS

Symbol	Parameter <sup>(1)</sup>	Test Conditions		Min.	Typ. <sup>(2)</sup>	Max.	Unit
I <sub>BHH</sub>	Bus-Hold Input Sustain Current	V <sub>CC</sub> = 3.0V	V <sub>I</sub> = 2.0V	- 75	—	—	μA
			V <sub>I</sub> = 0.8V	75	—	—	
I <sub>BHL</sub>	Bus-Hold Input Sustain Current	V <sub>CC</sub> = 2.3V	V <sub>I</sub> = 1.7V	- 45	—	—	μA
			V <sub>I</sub> = 0.7V	45	—	—	
I <sub>BHNO</sub>	Bus-Hold Input Overdrive Current	V <sub>CC</sub> = 3.6V	V <sub>I</sub> = 0 to 3.6V	—	—	± 500	μA
I <sub>BHLO</sub>							

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**NOTES:**

1. Pins with Bus-hold are identified in the pin description.
2. Typical values are at V<sub>CC</sub> = 3.3V, +25 °C ambient.

**OUTPUT DRIVE CHARACTERISTICS**

Symbol	Parameter	Test Conditions <sup>(1)</sup>		Min.	Max.	Unit
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> = 2.3V to 3.6V	I <sub>OH</sub> = -0.1mA	V <sub>CC</sub> - 0.2	—	V
		V <sub>CC</sub> = 2.3V	I <sub>OH</sub> = -6mA	2	—	
		V <sub>CC</sub> = 2.3V	I <sub>OH</sub> = -12mA	1.7	—	
		V <sub>CC</sub> = 2.7V		2.2	—	
		V <sub>CC</sub> = 3.0V		2.4	—	
		V <sub>CC</sub> = 3.0V	I <sub>OH</sub> = -24mA	2	—	
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = 2.3V to 3.6V	I <sub>OL</sub> = 0.1mA	—	0.2	V
		V <sub>CC</sub> = 2.3V	I <sub>OL</sub> = 6mA	—	0.4	
			I <sub>OL</sub> = 12mA	—	0.7	
		V <sub>CC</sub> = 2.7V	I <sub>OL</sub> = 12mA	—	0.4	
		V <sub>CC</sub> = 3.0V	I <sub>OL</sub> = 24mA	—	0.55	

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**NOTE:**

- V<sub>IH</sub> and V<sub>IL</sub> must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate V<sub>CC</sub> range. T<sub>A</sub> = -40°C to +85°C.

**OPERATING CHARACTERISTICS, T<sub>A</sub> = 25°C**

Symbol	Parameter	Test Conditions	V <sub>CC</sub> = 2.5V ± 0.2V	V <sub>CC</sub> = 3.3V ± 0.3V	Unit
			Typical	Typical	
CPD	Power Dissipation Capacitance Outputs enabled	C <sub>L</sub> = 0pF, f = 10Mhz	55	59	pF
CPD	Power Dissipation Capacitance Outputs disabled		46	49	pF

## SWITCHING CHARACTERISTICS (1)

Symbol	Parameter	Vcc = 2.5V ± 0.2V		Vcc = 2.7V		Vcc = 3.3V ± 0.3V		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
tPLH tPHL	Propagation Delay CLK to 1Bx or CLK to 2Bx	1.5	5	1.5	4.7	1.5	4.3	ns
tPLH tPHL	Propagation Delay CLK to Ax, SEL stable and $\overline{\text{CExB}}$ enabled	1.5	5.3	1.5	5	1.5	4.6	ns
tPLH tPHL	Propagation Delay SEL changing and $\overline{\text{CExB}}$ disabled	1.5	5.7	1.5	5.3	1.5	5.1	ns
tPLH tPHL	Propagation Delay SEL changing and $\overline{\text{CExB}}$ enabled	1.5	5.8	1.5	5.4	1.5	5.1	ns
tpZH tpZL	Output Enable Time CLK to Ax, CLK to 1Bx, or CLK to 2Bx	1.5	5.6	1.5	5.2	1.5	5	ns
tpHZ tpLZ	Output Disable Time CLK to Ax, CLK to 1Bx, or CLK to 2Bx	1.3	4.7	1.5	5.2	1.5	5	ns
tsu	Setup Time, data to CLK, HIGH or LOW	1	—	1	—	1	—	ns
tsu	Setup Time, $\overline{\text{OEA}}$ to CLK, $\overline{\text{OEB}}$ to CLK	1	—	1	—	1	—	ns
tsu	Setup Time, SEL to CLK	1	—	1	—	1	—	ns
tsu	Setup Time, $\overline{\text{CEA1B}}$ to CLK, $\overline{\text{CE1B}}$ to CLK, $\overline{\text{CE2B}}$ to CLK, or $\overline{\text{CEA2B}}$ to CLK	1	—	1	—	1	—	ns
th	Hold Time, CLK to data	1	—	1	—	1	—	ns
th	Hold Time, CLK to $\overline{\text{OEA}}$ , CLK to $\overline{\text{OEB}}$ , CLK to SEL	1	—	1	—	1	—	ns
th	Hold Time, CLK to $\overline{\text{CEA1B}}$ , CLK to $\overline{\text{CE1B}}$ , CLK to $\overline{\text{CE2B}}$ , CLK to $\overline{\text{CEA2B}}$	1	—	1	—	1	—	ns
tw	Pulse Width, CLK HIGH	2.5	—	2.5	—	2.5	—	ns
tsk(o)	Output Skew <sup>(2)</sup>	—	—	—	—	—	500	ps

### NOTES:

1. See test circuits and waveforms.  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ .
2. Skew between any two outputs of the same package and switching in the same direction.

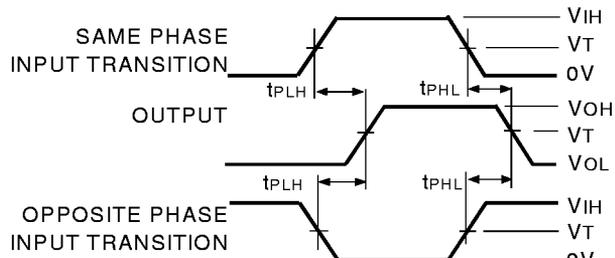
## TEST CIRCUITS AND WAVEFORMS

### TEST CONDITIONS

Symbol	V <sub>CC</sub> (1)= 3.3V±0.3V	V <sub>CC</sub> (1)= 2.7V	V <sub>CC</sub> (2)= 2.5V±0.2V	Unit
V <sub>LOAD</sub>	6	6	2 x V <sub>CC</sub>	V
V <sub>IH</sub>	2.7	2.7	V <sub>CC</sub>	V
V <sub>T</sub>	1.5	1.5	V <sub>CC</sub> / 2	V
V <sub>LZ</sub>	300	300	150	mV
V <sub>HZ</sub>	300	300	150	mV
C <sub>L</sub>	50	50	30	pF

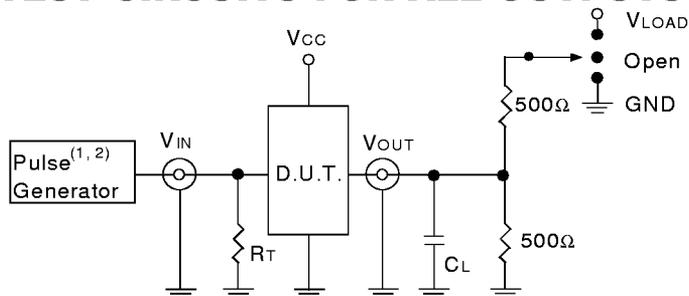
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### PROPAGATION DELAY



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### TEST CIRCUITS FOR ALL OUTPUTS



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#### DEFINITIONS:

C<sub>L</sub> = Load capacitance: includes jig and probe capacitance.  
R<sub>T</sub> = Termination resistance: should be equal to Z<sub>OUT</sub> of the Pulse Generator.

#### NOTES:

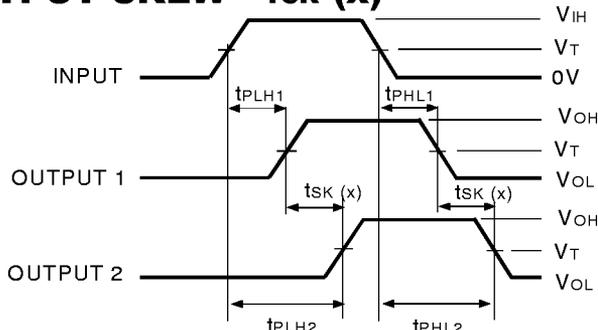
1. Pulse Generator for All Pulses: Rate ≤ 10MHz; t<sub>F</sub> ≤ 2.5ns; t<sub>R</sub> ≤ 2.5ns.
2. Pulse Generator for All Pulses: Rate ≤ 10MHz; t<sub>F</sub> ≤ 2ns; t<sub>R</sub> ≤ 2ns.

### SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	V <sub>LOAD</sub>
Disable High Enable High	GND
All Other tests	Open

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### OUTPUT SKEW - t<sub>SK</sub>(x)



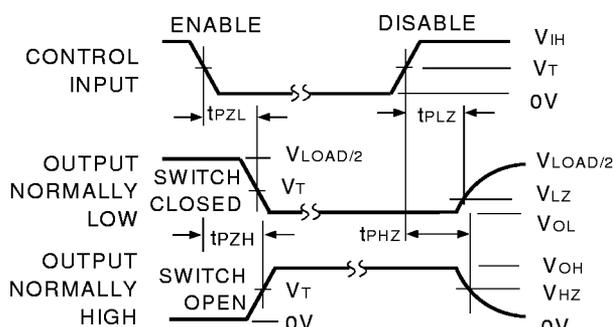
$$t_{SK}(x) = |t_{PLH2} - t_{PLH1}| \text{ or } |t_{PHL2} - t_{PHL1}|$$

ALVC Link

#### NOTES:

1. For t<sub>SK</sub>(o) OUTPUT1 and OUTPUT2 are any two outputs.
2. For t<sub>SK</sub>(b) OUTPUT1 and OUTPUT2 are in the same bank.

### ENABLE AND DISABLE TIMES

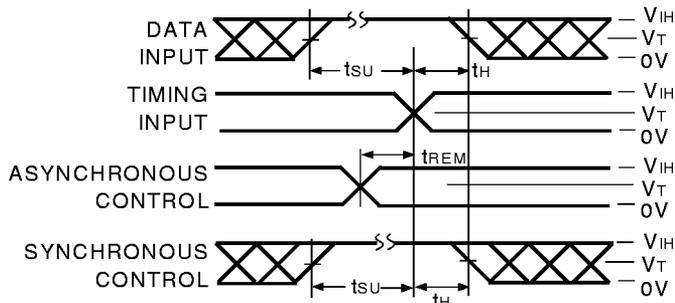


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#### NOTE:

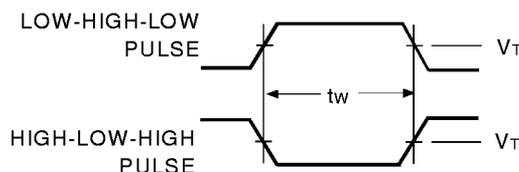
1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

### SET-UP, HOLD, AND RELEASE TIMES



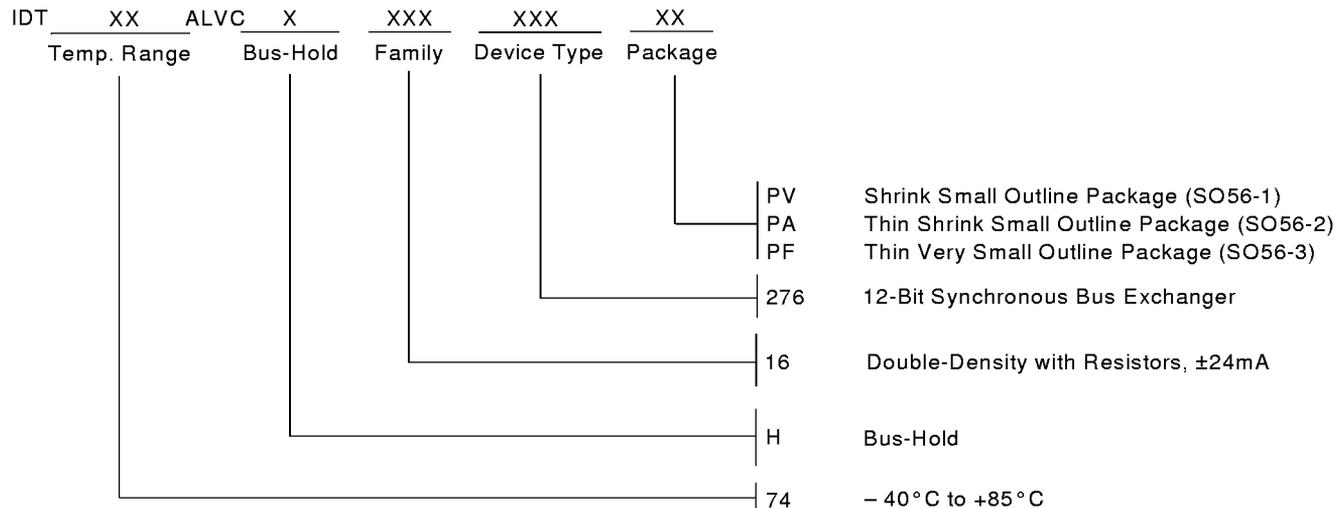
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### PULSE WIDTH



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**ORDERING INFORMATION**



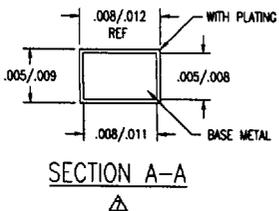
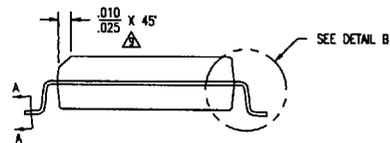
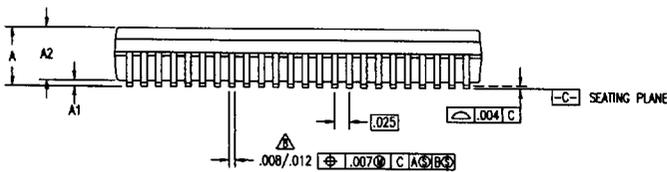
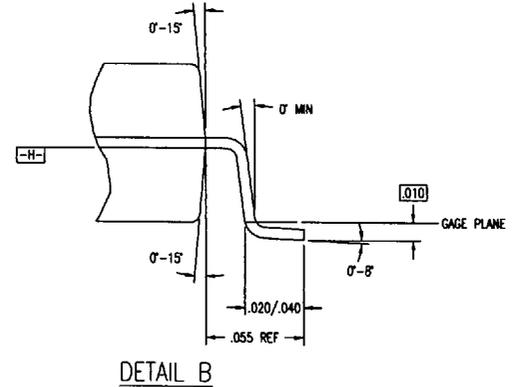
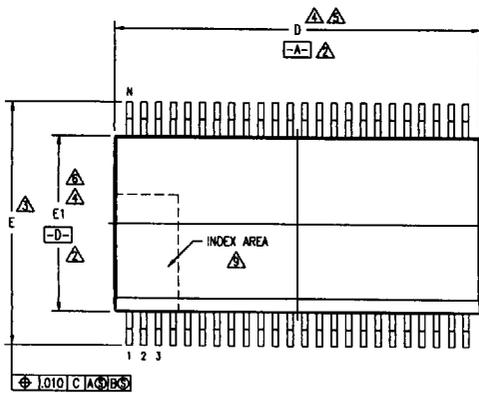
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PACKAGE DIAGRAM OUTLINES  
SSOP

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
17893	00	INITIAL RELEASE	07/15/90	A. FUNCELL
22377	01	REMOVE CHAMFER FROM PACKAGE	04/15/92	T. WJ
27492	02	REDRAW TO JEDEC FORMAT	02/01/95	



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DECIMAL	ANGULAR	TITLE PV PACKAGE OUTLINE	
XXX	±	.300" BODY WIDTH SSOP	
XXXX		.025" PITCH	
XXXXX		APPROVALS	DATE
		DRWN <i>AA</i>	08/15/90
CHECKED		SIZE	DRAWING No.
		C	PSC-4029
		REV	02
DO NOT SCALE DRAWING			

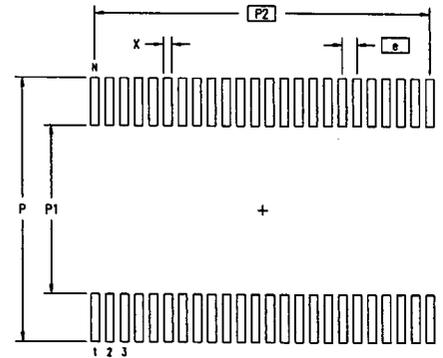
PACKAGE DIAGRAM OUTLINES

SSOP (Continued)

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
17893	00	INITIAL RELEASE	07/15/90	A. FUNCELL
22377	01	REMOVE CHAMFER FROM PACKAGE	04/15/92	T. WU
27492	02	REDRAW TO JEDEC FORMAT	02/01/95	

SYMBOL	DWG # S048-1				DWG # S056-1			
	JEDEC VARIATION			NOTE	JEDEC VARIATION			NOTE
	AA				AB			
	MIN	NOM	MAX		MIN	NOM	MAX	
A	.095	.102	.110		.095	.102	.110	
A1	.008	.012	.016		.008	.012	.016	
A2	.088	.090	.092		.088	.090	.092	
D	.620	.625	.630	4,5	.720	.725	.730	4,5
E	.395	.405	.420	3	.395	.405	.420	3
E1	.291	.295	.299	4,6	.291	.295	.299	4,6
N	48				56			

LAND PATTERN DIMENSIONS



	MIN	MAX	MIN	MAX
P	.450	.458	.450	.458
P1	.282	.290	.282	.290
P2	.575 BSC		.675 BSC	
X	.010	.018	.010	.018
e	.025 BSC		.025 BSC	
N	48		56	

NOTES:

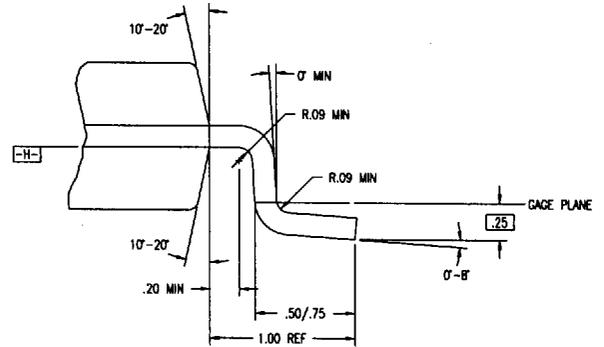
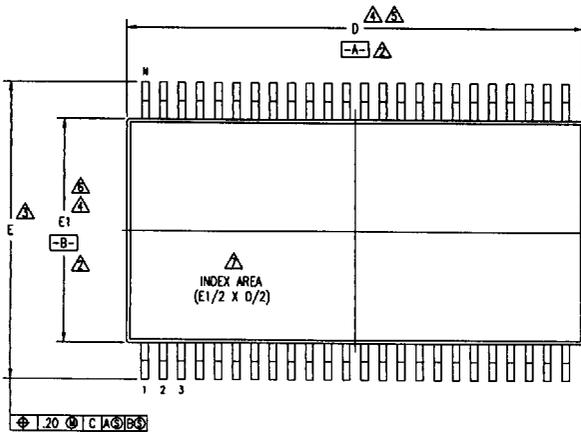
- ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- DATUMS **-A-** AND **-B-** TO BE DETERMINED AT DATUM PLANE **-H-**
- DIMENSION E TO BE DETERMINED AT SEATING PLANE **-C-**
- DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE **-H-**
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 PER SIDE
- DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .015 PER SIDE
- THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND .010 FROM LEAD TIP
- LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .004 IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- THE CHAMFER ON THE PACKAGE BODY IS OPTIONAL. IF IT IS NOT PRESENT, A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE ZONE INDICATED
- ALL DIMENSIONS ARE IN INCHES
- THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-118, VARIATION AA & AB

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DECIMAL	ANGULAR		
X.XX	±		
X.XXX			
X.XXX			
APPROVALS	DATE	TITLE	
DRAWN <i>Ad</i>	08/15/90	PV PACKAGE OUTLINE .300" BODY WIDTH SSOP .025" PITCH	
CHECKED		SIZE	REV
		C	02
		DRAWING No.	
		PSC-4029	
DO NOT SCALE DRAWING			

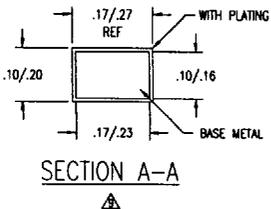
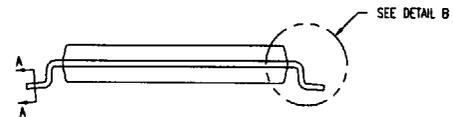
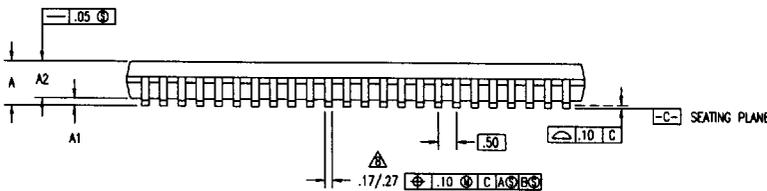
PACKAGE DIAGRAM OUTLINES

TSSOP

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
23757	00	INITIAL RELEASE	02/15/93	T. VJ
26315	01	CHANGE DIMS A1 & A2	05/18/94	DG
26490	02	CHANGE DIM A1	07/21/94	T. VJ
27494	03	REDRAW TO JEDEC FORMAT	03/06/95	



DETAIL B



SECTION A-A

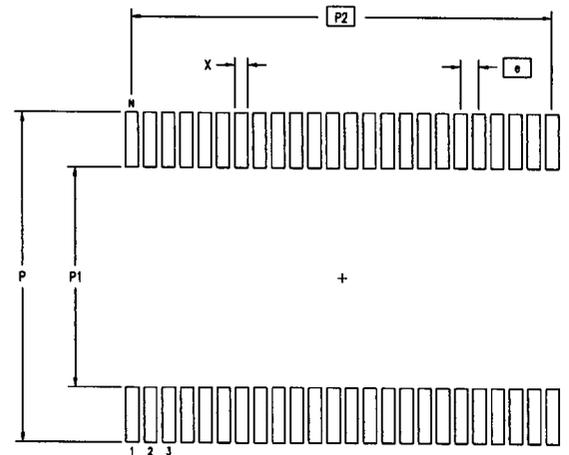
TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc. 2975 Slender Way, Santa Clara, CA 95054 PHONE: (408) 727-8118 FAX: (408) 492-8674 TWC: 910-338-2070
DECIMAL	ANGULAR	
$\pm .004$	$\pm .05$	
APPROVALS		TITLE PA PACKAGE OUTLINE
DRAWN <i>dd</i>		6.10 mm BODY WIDTH TSSOP
CHECKED		.50 mm PITCH
SIZE	DRAWING No.	REV
C	PSC-4039	03
DO NOT SCALE DRAWING		

PACKAGE DIAGRAM OUTLINES  
TSSOP (Continued)

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
23757	00	INITIAL RELEASE	02/15/93	T. WU
26315	01	CHANGE DIMS A1 & A2	05/18/94	DG
26490	02	CHANGE DIM A1	07/21/94	T. WU
27494	03	REDRAW TO JEDEC FORMAT	03/08/95	

SYMBOL	DWG # S048-2			NOTE	DWG # S056-2			NOTE		
	JEDEC VARIATION				JEDEC VARIATION					
	ED	EE			ED	EE				
MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX		
A	-	-	1.10	-	-	1.10	-	-	1.10	
A1	.05	-	.15	.05	-	.15	.05	-	.15	
A2	.85	1.00	1.05	.85	1.00	1.05	.85	1.00	1.05	
D	12.40	12.50	12.60	4,5	13.90	14.00	14.10	4,5		
E	7.95	8.10	8.25	3	7.95	8.10	8.25	3		
E1	6.00	6.10	6.20	4,6	6.00	6.10	6.20	4,6		
N	48				56					

LAND PATTERN DIMENSIONS



	MIN	MAX	MIN	MAX
P	8.90	9.10	8.90	9.10
P1	5.90	6.10	5.90	6.10
P2	11.50 BSC		13.50 BSC	
X	.30	.40	.30	.40
e	.50 BSC		.50 BSC	
N	48		56	

NOTES:

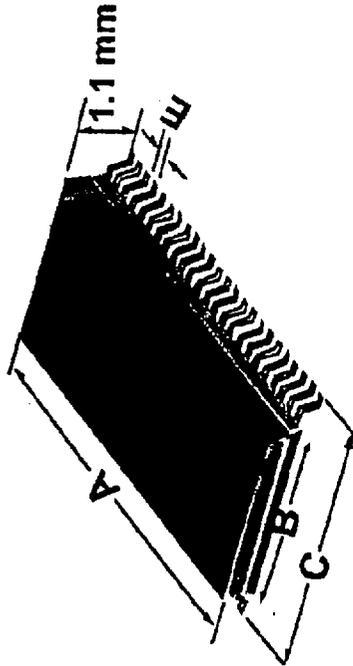
- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- △ DATUMS  $\square$ -A- AND  $\square$ -B- TO BE DETERMINED AT DATUM PLANE  $\square$ -H-
- △ DIMENSION E TO BE DETERMINED AT SEATING PLANE  $\square$ -C-
- △ DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE  $\square$ -H-
- △ DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE
- △ DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .25 mm PER SIDE
- △ DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
- △ LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- △ THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
- 10 ALL DIMENSIONS ARE IN MILLIMETERS
- 11 THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MQ-153, VARIATION ED & EE

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.	
DECIMAL	ANGULAR	2975 Slender Way, Santa Clara, CA 95054	
±	±	PHONE: (408) 727-8118	
		FAK: (408) 482-8874	TWX: 910-338-2070
APPROVALS	DATE	TITLE PA PACKAGE OUTLINE	
DRAWN	01/19/93	6.10 mm BODY WIDTH TSSOP	
CHECKED		.50 mm PITCH	
		SIZE C	DRAWING No. PSC-4039
			REV 03
DO NOT SCALE DRAWING			



# TVSOP

## The Most Compact Double Density Package

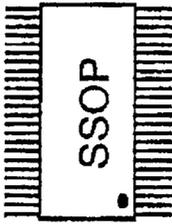


TVSOP Package	Typical Dimensions (in mm)				Area (mm <sup>2</sup> )
	A	B	C	E	
48 Pin	9.80	4.40	6.40	0.40	63.00
56 Pin	11.30	4.40	6.40	0.40	72.30
80 Pin	17.00	6.10	8.10	0.40	137.80
100 Pin	20.80	6.10	8.10	0.40	168.50



# Double Density Packaging

## 48-Pin



16.0 x 10.3 x 2.6 mm  
pin pitch = 0.635 mm  
Area = 164.8 mm<sup>2</sup>

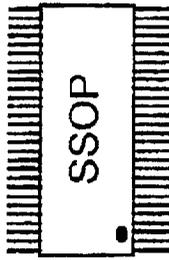


12.5 x 8.1 x 1.1 mm  
pin-pitch = 0.5 mm  
Area = 101.3 mm<sup>2</sup>



9.8 x 6.4 x 1.1 mm  
pin-pitch = 0.4 mm  
Area = 62.7 mm<sup>2</sup>

## 56-Pin



18.4 x 10.3 x 2.6 mm  
pin-pitch = 0.635 mm  
Area = 189.5 mm<sup>2</sup>



14.0 x 8.1 x 1.1 mm  
pin-pitch = 0.5 mm  
Area = 113.4 mm<sup>2</sup>



11.3 x 6.4 x 1.1 mm  
pin-pitch = 0.4 mm  
Area = 72.3 mm<sup>2</sup>

TVSOP	Area (mm <sup>2</sup> )	%Smaller Than SSOP	%Smaller Than TSSOP
48 pin	63.00	61.9	38.0
56 pin	72.30	62.2	36.0